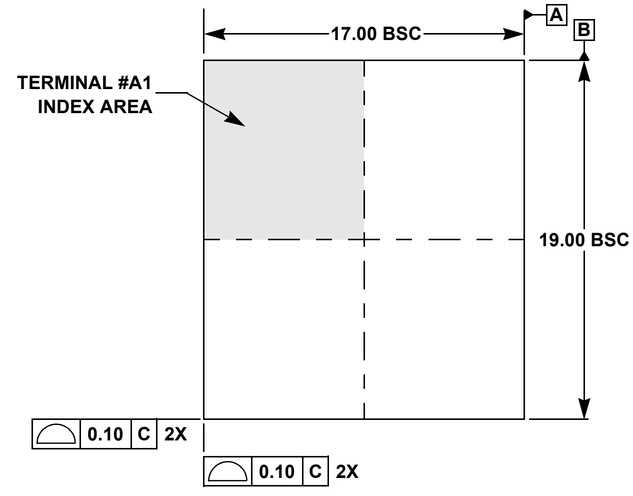
Package Outline Drawing

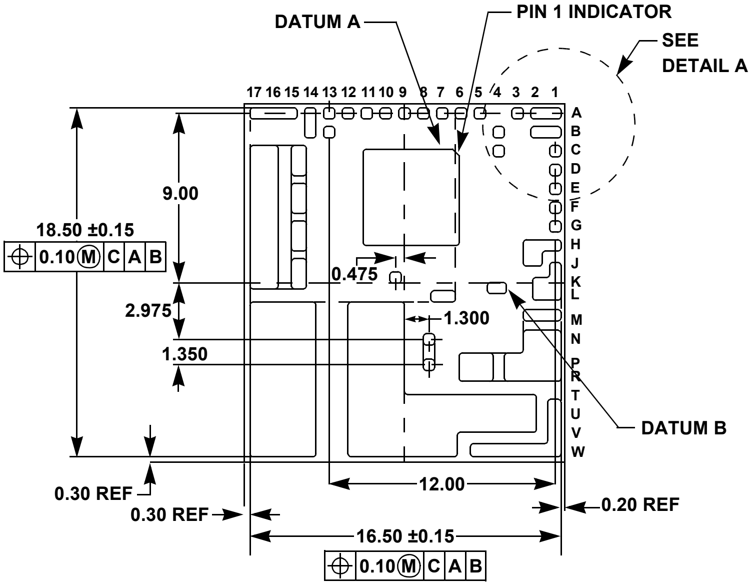
Y41.17x19

41 I/O 17.0mm x 19.0mmx3.6mm HDA MODULE

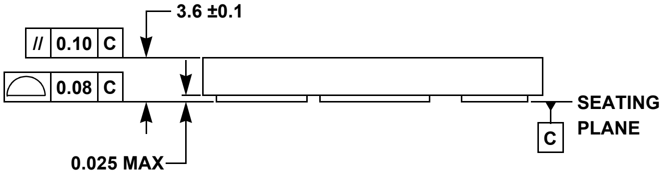
Rev 1, 5/16



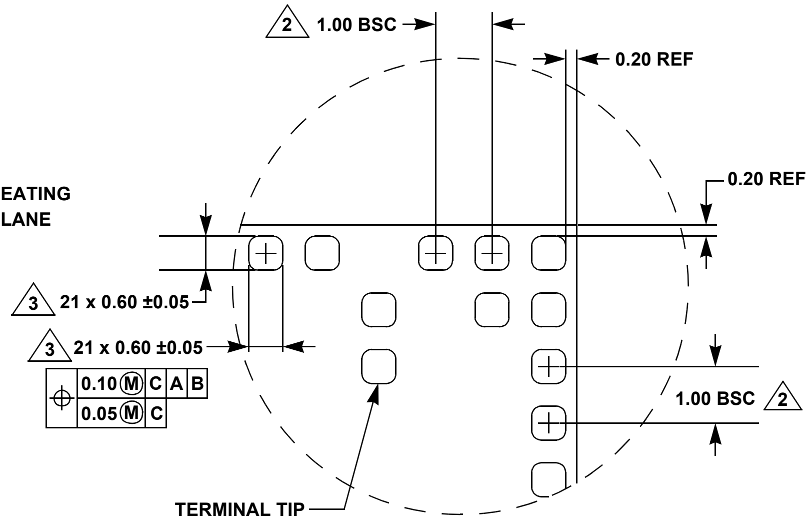
TOP VIEW



BOTTOM VIEW



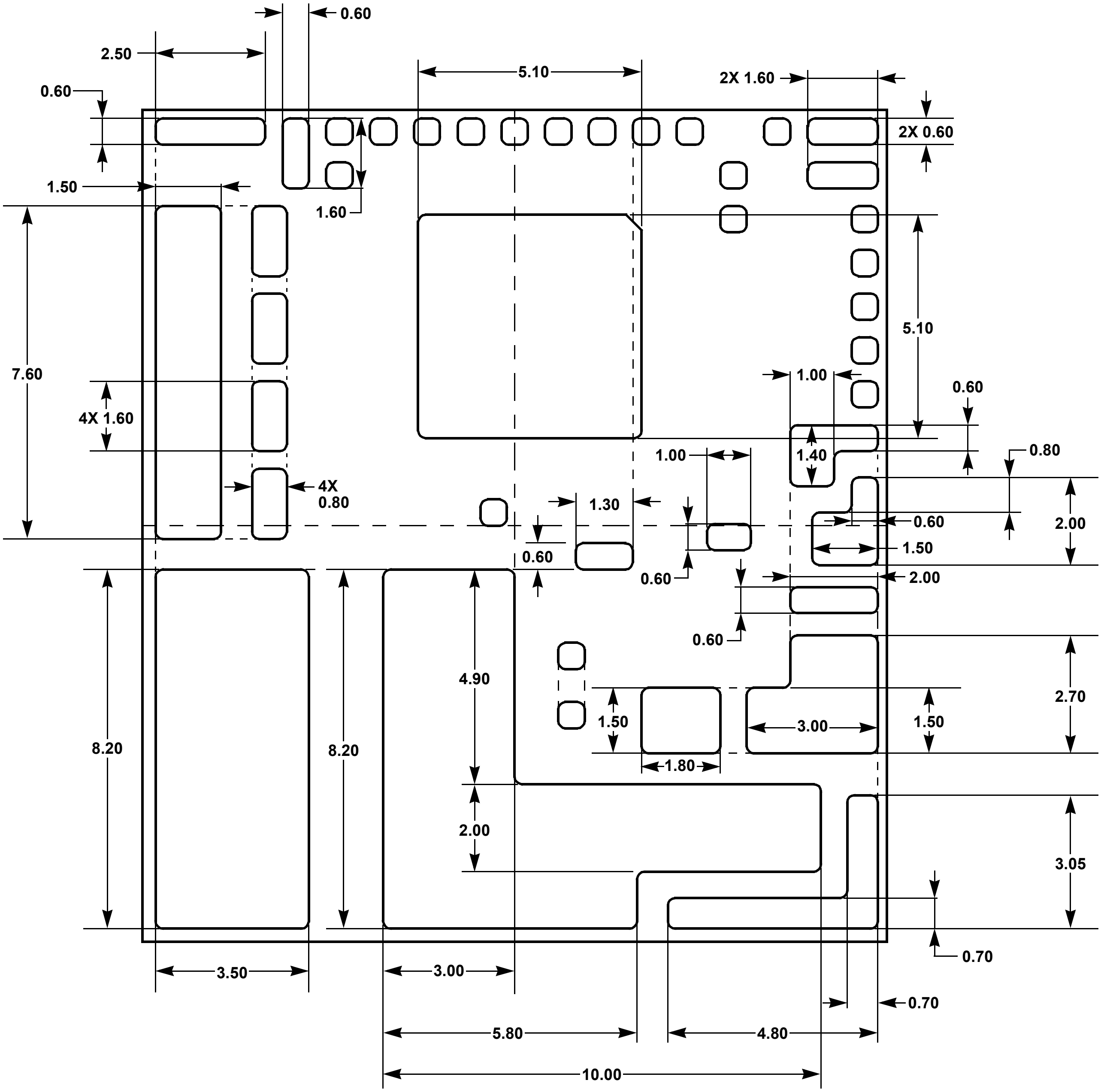
SIDE VIEW



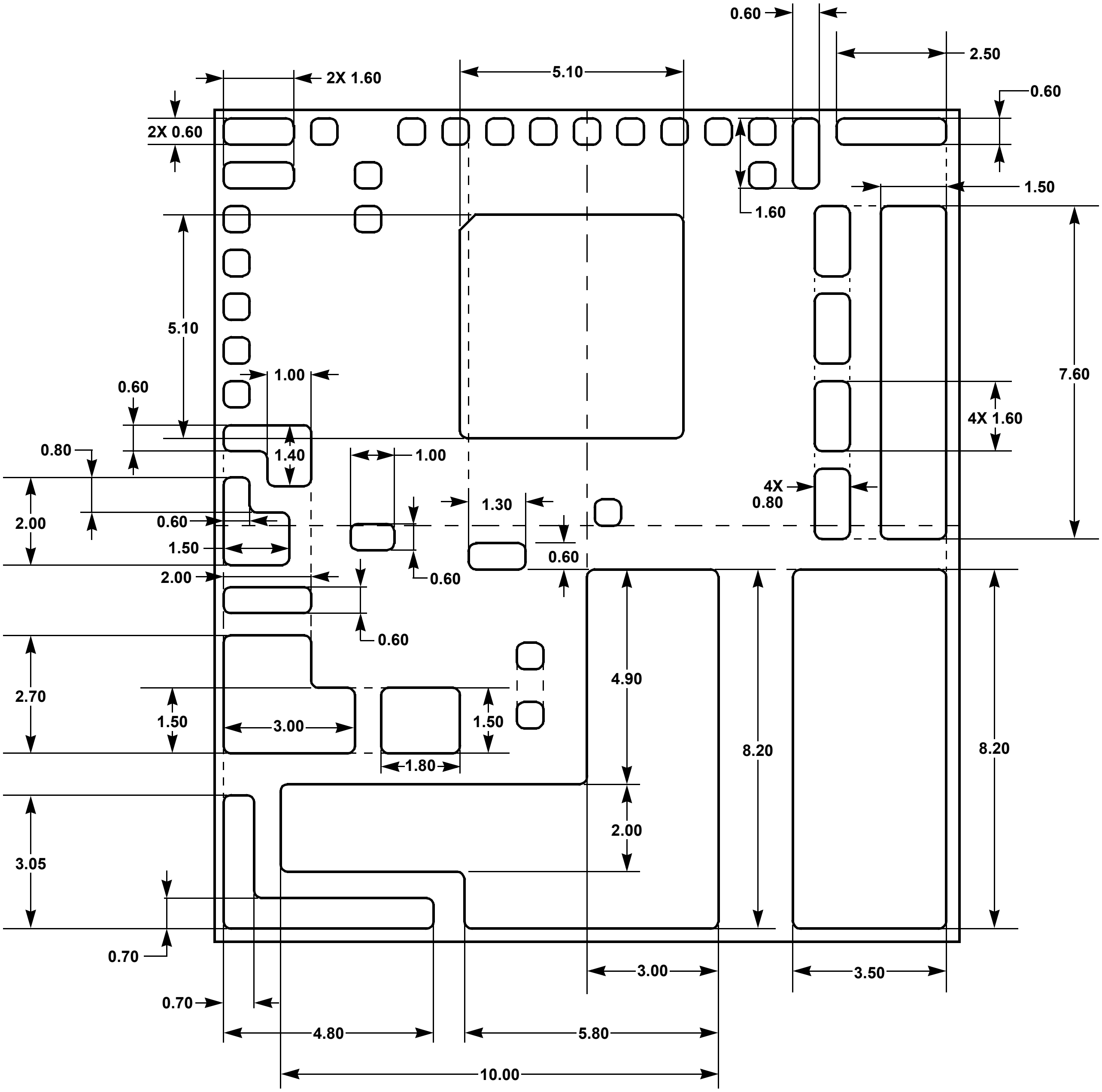
DETAIL A

NOTES:

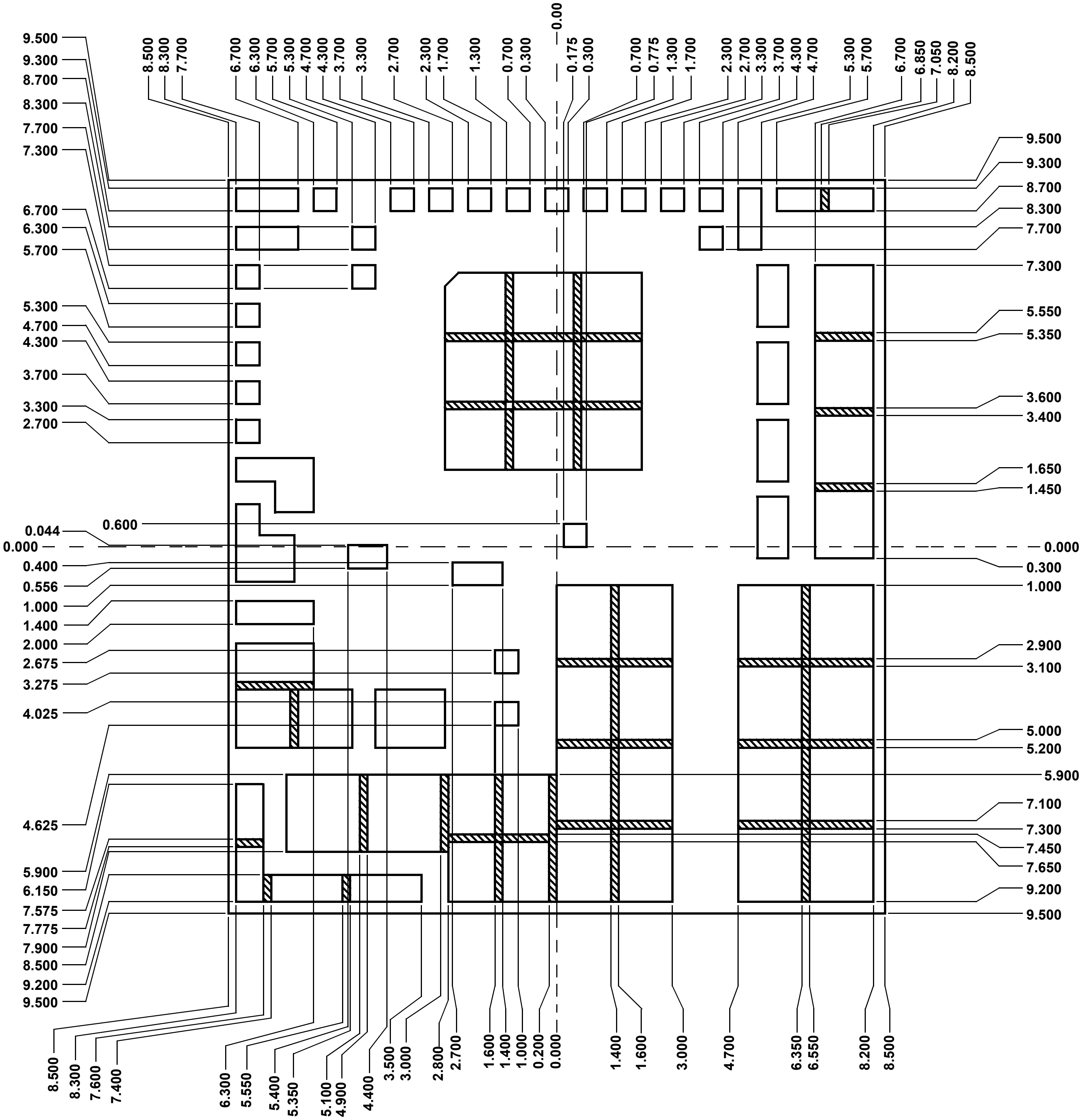
1. All dimensions are in millimeters.
2. Represents the basic land grid pitch.
3. The total number of I/O (excluding dummy pads).
4. Unless otherwise specified, tolerance: decimal ±0.10.
5. Dimensioning and tolerancing per ASME Y14.M-2009.
6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated.
   The pin #1 identifier may be either a mold or mark feature.



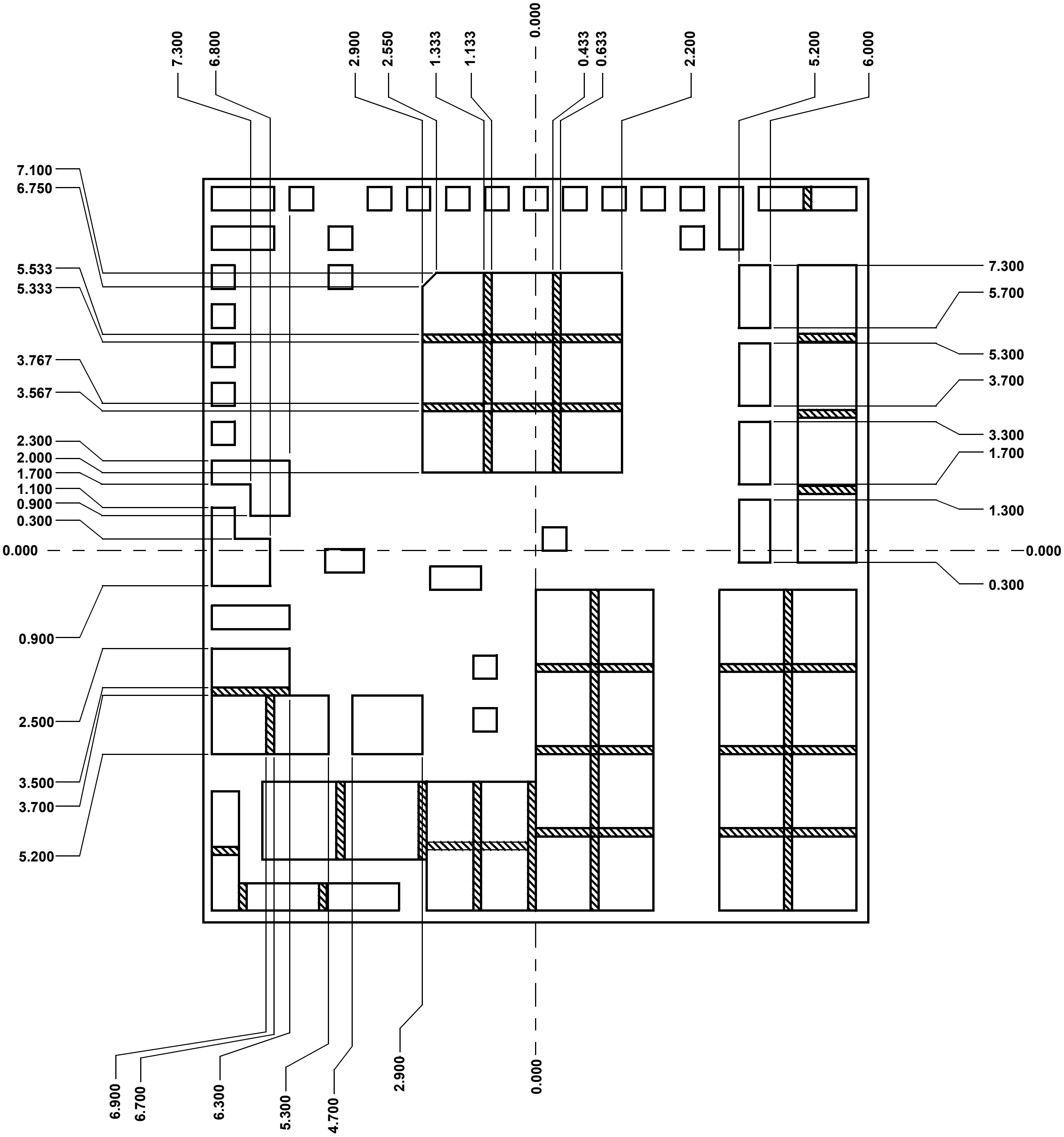
SIZE DETAILS FOR THE 16 EXPOSED DAPS
BOTTOM VIEW



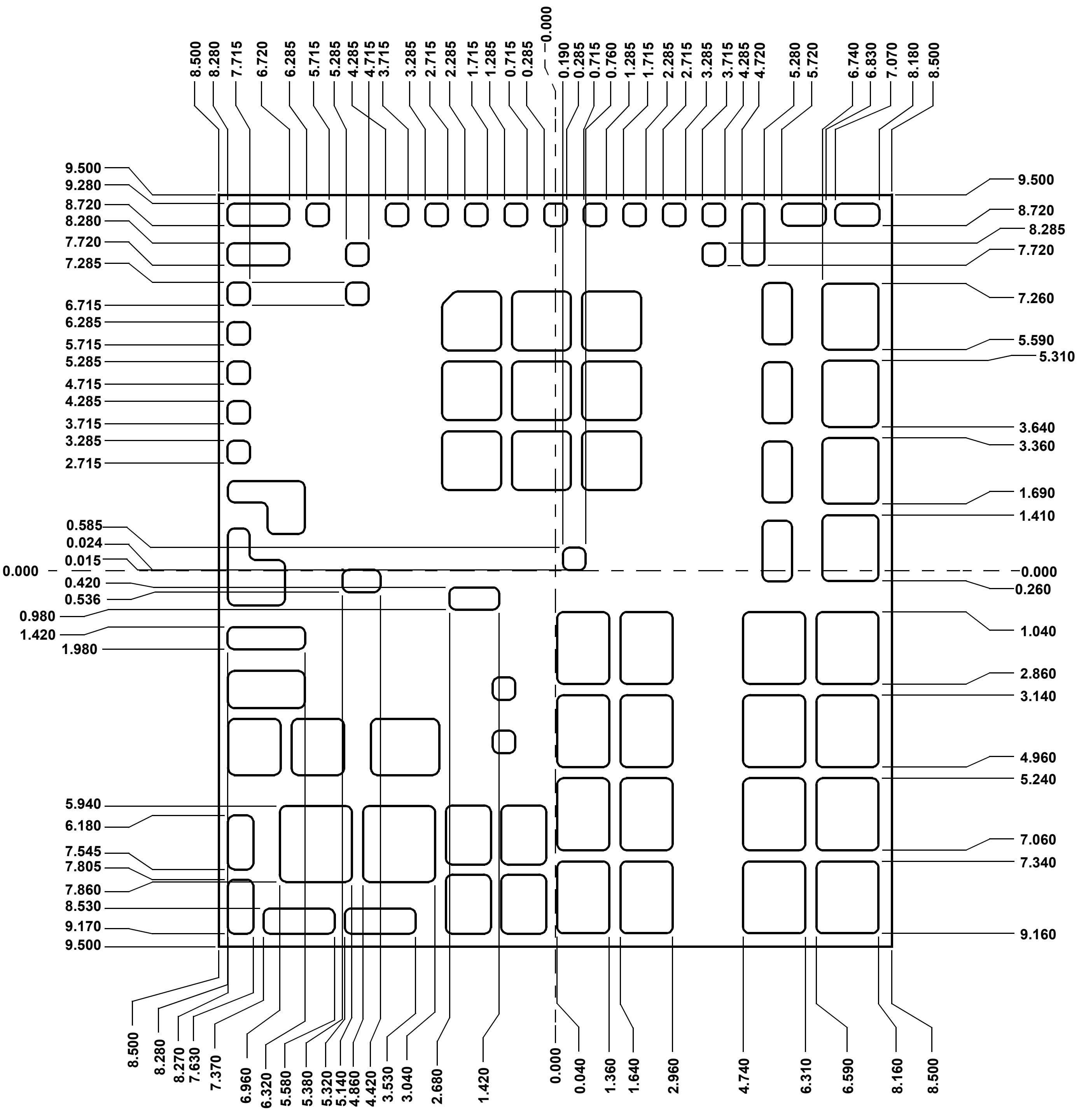
SIZE DETAILS FOR THE 16 EXPOSED DAPS
TOP VIEW



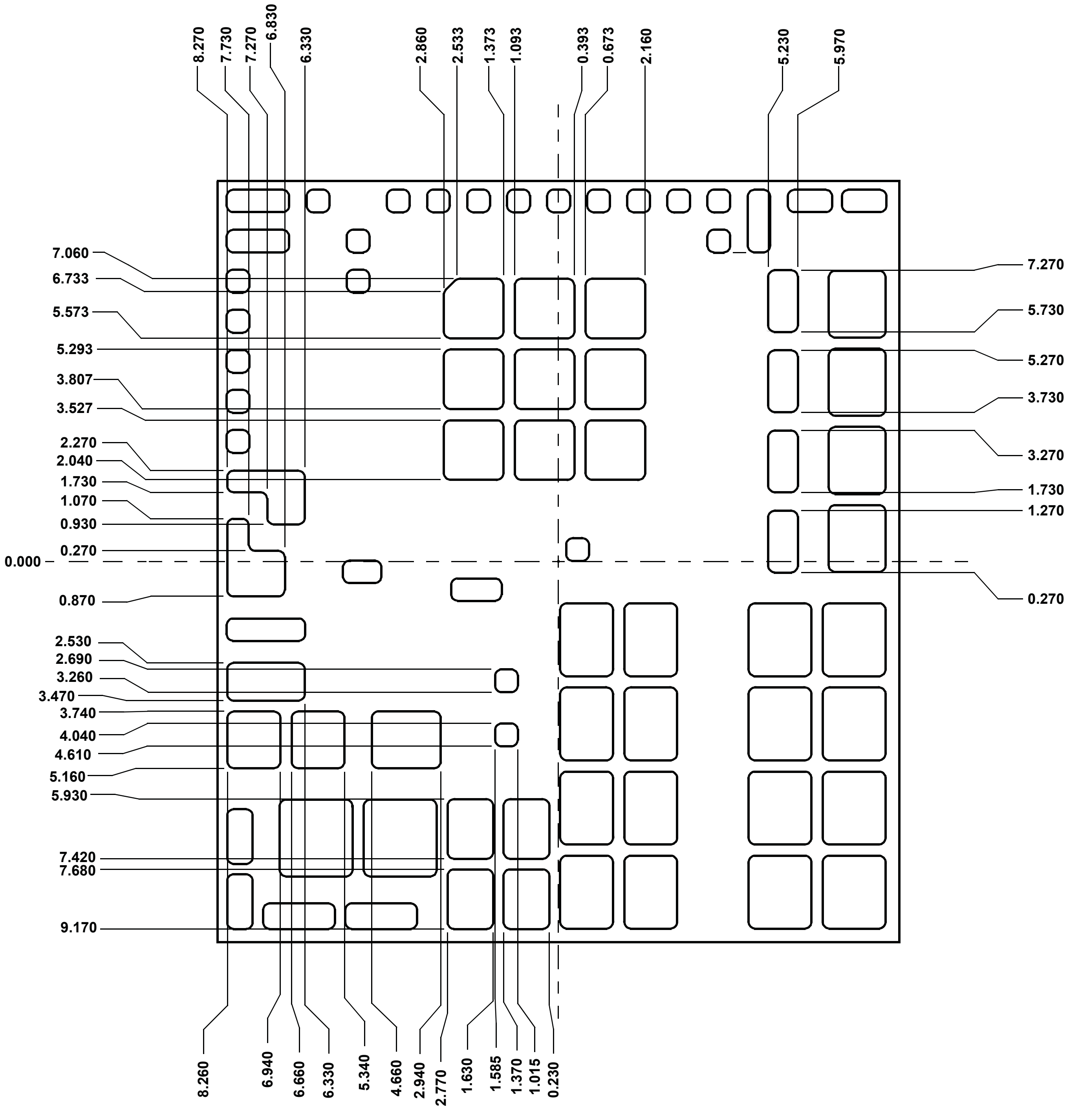
RECOMMENDED SOLDER MASK DEFINED PCB LAND PATTERN (1)
TOP VIEW



RECOMMENDED SOLDER MASK DEFINED PCB LAND PATTERN (2)
TOP VIEW



RECOMMENDED STENCIL PATTERN (90% PASTE TO PAD) (1)
TOP VIEW



RECOMMENDED STENCIL PATTERN (90% PASTE TO PAD) (2)
TOP VIEW